



ADVANCED SYSTEM IN PACKAGE TECHNOLOGY
CONFERENCE & EXHIBITION

BROUGHT TO YOU BY IMAPS

June 21 – 23, 2022 • Sonoma, California USA • Doubletree by Hilton

www.ADVANCEDSIP.org

ADVANCED SiP 2022 OVERVIEW



General Co-Chairs

Mark Gerber
ASE Group

General Chair-elect

Steven Kummerl
Texas Instruments

IMAPS VP Technology

Jon Aday
Amkor Technology

Advanced SiP 2022 is a continuation of IMAPS SiP Conference which first started in June 2017 as the first System-in-Package (SiP) conference fully dedicated to covering all aspects related to SiPs - market trends, system integration/miniaturization, and new technology innovation enablers to meet current and future SiP challenges.

This conference will bring the entire SiP supply and design chain from OEM, Fabless, IDM, OSAT, EMS, EDA, silicon foundries, equipment and material suppliers together under one roof.

Speakers, sponsors, exhibitors and attendees will focus on the insights of SiP technology in relaxing Sonoma, California, away from big city distractions.

Featuring three full days of technical sessions, panel discussions, exhibitors and local activities, SiP 2022 will provide dynamic learning and technology updates for SiP related trends and new engineering innovations from the industry's world SiP leaders.

Speaking and presenting opportunities are by invitation from the technical committee. Additional committee members are:

Eelco Bergman, ASE

Curtis Zwenger, Amkor

Christo Bojkov, Qorvo

Habib Hichri, Ajinomoto

Mark Scannell, CEA LETI

Tarak Railkar, Qorvo

Jan Vardaman, TechSearch International

ADVANCED SiP 2022 KEY DATES AND LOCATION

Conference Dates

June 21-23, 2022

Technical Program	June 21-23
Exhibition	June 21-23
Start-Up Competition	June 21
Sip at SiP Dinner	June 22

Conference Location & Hotel

Doubletree by Hilton
Sonoma, California USA



Reservation details will be posted online soon.

TENTATIVE CONFERENCE PROGRAM AND ACTIVITIES SCHEDULE

Visit www.advancedsip.org for the release of the finalized advance program!

Tuesday, June 21	Wednesday, June 22	Thursday, June 23
<p>Special Activities Exhibits Open Start-up Competition Welcome Reception</p> <p>General Session</p> <ul style="list-style-type: none"> • Keynotes & Marketing and Technology Trends: SiP Trends in Cellphone, IoT, Automotive, Computing and Networking • System Integration in SiP: Challenges for Cellphone, IoT, Consumer, Automotive, Computing and Networking Products 	<p>Special Activities Exhibits Open</p> <p>General Session</p> <ul style="list-style-type: none"> • SiP Solutions for Cellphone, IoT and other Consumer products • Assembly and Manufacturing • SiP Assembly and Test • Design • Substrate, Material and Test for Cellphone, IoT and other consumer SiP Solutions • Research and Development 	<p>Special Activities Panel Discussion on SiP Challenges & Solutions</p> <p>General Session</p> <ul style="list-style-type: none"> • SiP Test and Design for Testability

Advanced SiP 2022 features sponsorship and exhibition opportunities that will reach key decision makers, influencers, and thought leaders in the advanced SiP technology ecosystem.

Anticipated Attendees:

C-Suite executives, directors, senior managers and engineers from OEM, Fabless, IDM, OSAT, EMS, EDA, silicon foundries, equipment and material suppliers

Attendee Exposure:

Sponsors and exhibitor tabletops are positioned in the pre-function space adjacent to the general session ballroom. Exhibitors enjoy opportunities to network with attendees during meals, breaks, and the conference welcome reception.

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Past SiP conferences attracted the following **sponsors and exhibitors**:

5N Plus Inc.

Ajinomoto Fine-Techno Co., Inc.

AkroMetrix, LLC

Amkor Technology

ASE Group

AT&S Americas, LLC

C&D Semiconductor Services Inc.

Cadence Design Systems, Inc.

DOW Electronic Materials

Dynatex International

EMD Performance Materials

Heraeus Precious Metals NAC

Indium Corporation

JCET Group

Kyocera International, Inc.

NAMICS Corporation

NTK Technologies

PacTech

QP Technologies

Samtec, Inc.

Sekisui Chemical Co., Ltd.

Shenmao America, Inc.

YXLON Feinfocus

Premier Sponsor
Corporate Sponsor

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Past SiP conferences attracted **attendees from these companies:**

3DiS	Dynatex International	KLA-Tencor Corporation	Quantum Wave Fund	TransSiP
5N Plus Inc.	EDA2ASIC	Kyocera America, Inc.	Recht Associates	U Blox
Advantest Corporation	EMD Performance Materials	Kyocera International, Inc.	Renesas Electronics Corporation	ViaSat
Ajinomoto Co., Inc.	ESI USA	Laird Technologies	Rex Computing	XPERI
AkroMetrix, LLC	FitBit	Linear Technology Corporation	Royce Instruments, LLC	Yole Developpement
Amazon	Flex	Lux Capital	Samtec, Inc.	YXLON Feinfocus
Amkor Technology	Fourth Dimension Engineering LLC	MEMSWork	Sekisui Chemical Co., Ltd.	ZESTRON
Apple	FRT of America, LLC	Mentor Graphics Corporation	Semblant	Zuken, Inc.
Applied Materials, Inc.	Fujimi	Metalor Technologies USA	Semiconductor Engineering	
ASE Group	Fulton Capital Advisors	MIT Lincoln Laboratory	Sencio	
Astronics Test Systems	Futurewei Technologies	NAMICS Corporation	Shenmao America Inc	
AT&S Americas, LLC	Henkel Corporation	NANIUM S.A.	Silicon Catalyst	
BAE Systems	Heraeus Electronics	National Instruments Corporation	Siliconware Precision Industries Co, Ltd.	
Broadcom Corp.	Huawei Technologies	Nitto Americas, Inc.	Simmtech Co., Ltd.	
BroadPak Corp	Ibiden Co., Ltd.	NTK Technologies, Inc.	Starkey Hearing Technologies	
C&D Semiconductor Services, Inc.	In Charge Around Here	ON Semiconductor Corporation	STATS ChipPAC, Inc.	
C.S. Draper Labs	Indium Corporation	Pac Tech Packaging Technologies USA	SUMITOMO CHEMICAL	
Cadence Design Systems, Inc.	Infineon Technologies	Power Integrations, Inc.	Sumitomo Plastics America Inc.	
CEA LETI-Minatec	Insight SiP	QP Technologies	SVXR Inc.	
Chip Scale Review	Intel Corporation	Qorvo	TechSearch International, Inc.	
Cypress Semiconductor Corporation	Jabil Circuit, Inc.	Qualcomm, Inc.	Texas Instruments, Inc.	
Dell Computer Corporation	JCET Group		Towa Corporation	
DOW	Kinsus Corp			
DuPont Microcircuit Materials				

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Past SiP conferences attracted **attendees with these job titles:**

Account Manager	Executive Vice President	Product Management Director	Sr. Dr Business Development
Area Manager	General Manager	QA Manager	Sr. Manager of FAE
Assistant Product Manager	Global Director New Business Development	Regional Manager	Sr. Staff Packaging Engineer
Assistant Marcom Manager	Manager of Customer Support	Regional Product Manager – Semiconductor	Sr. Account Manager
Associate Staff	Market Development Manager	Research Chemist	Sr. Director Advanced Test R&D
Business Development Manager	Market Development Specialist	Sales Applications Engineer	Sr. Manager - New Business
Business Group Director	Marketing Director	Sales Department Manager	Development
Business President	Marketing Manager	Sales Manager	Sr. Package Engineer
CEO	Marketing Specialist	Semiconductor Packaging Lead	Staff Packaging Engineer
Chief Consultant	Microelectronics Program Manager	Senior Director	Technical Account Manager
Chief Technology Officer	Package Engineer	Senior Director of Engineering	Technical Director
Communications Manager	Packaging Engineer	Senior Engineering Manager	Vice President
Consultant	Partner	Senior Manager	Vice President, Business Unit
Deputy Director	President	Senior Manager, Advanced Packaging	Manager
DFM Engineer	President and CTO	Senior Mechanical Engineer	VP & Chief Marketing Officer
Director	Principal Engineer	Microelectronic Packaging Eng	VP Engineering
Director of Business Development	Principal Packaging Application Consultant	Senior Staff Engineer	VP of Sales & Marketing
Director of Research and Development	Process Engineer	SIP Innovation & Integration Manager	VP Technology
Director Technology	Product and Technology Marketing	Sr. Director, Sales	VP, APD/Electrical Engineering

Get face to face with these attendees as a sponsor or exhibitor

PREMIER SPONSOR

EVENT SPONSOR FOR

Welcome reception sponsor

-and-

Conference lunch sponsor (one day)

RECOGNITION

Lanyard co-sponsorship

Web ad on SiP webpage

Final program full page ad

Conference and event signage

Leading logo exposure on the SiP webpage, marketing emails, final program, and all applicable outlets

EXTRA BENEFITS

Up to two tabletop exhibit spaces

Four (4) complimentary registrations

Two (2) complimentary wine event tickets

Collateral distribution on site (provided by sponsor)

\$10,000

Max 2 available

PRESENTING SPONSOR

EVENT SPONSOR FOR

Conference breakfast sponsor (one day)

-and-

Conference morning break sponsor (one day)

RECOGNITION

Web ad on SiP webpage

Final program half page ad

Conference and event signage

Leading logo exposure on the SiP webpage, marketing emails, final program, and all applicable outlets

EXTRA BENEFITS

One tabletop exhibit space

Two (2) complimentary registrations

One (1) complimentary wine event ticket

\$7,500

Max 3 available

START-UP COMPETITION SPONSOR

EVENT SPONSOR FOR

Start-Up competition and refreshments

RECOGNITION

Event signage

Logo exposure on the SiP webpage, marketing emails, final program, and all applicable outlets

BENEFITS

Final program full page ad for a sole sponsor or a quarter page ad for a co-sponsor

Web ad on SiP webpage

\$2,500 or \$10,000

Max 5 co-sponsors or one sole

SIP AT WINE EVENT SPONSOR

EVENT SPONSOR FOR

Sip at wine event

RECOGNITION

Event signage

Web ad on SiP webpage
Logo exposure on the SiP webpage, marketing emails, final program, and all applicable outlets

BENEFITS

Final program half page ad for a sole sponsor or a quarter page ad for a co-sponsor

\$2,500 or \$5,000

Max 3 co-sponsors or one sole



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Sponsorship and Exhibit Opportunities

AFTERNOON COFFEE BREAK SPONSOR

EVENT SPONSOR FOR

Afternoon coffee breaks (One sole sponsor per break)

RECOGNITION

Event signage

Logo exposure on the SiP webpage, marketing emails, final program, and all applicable outlets

BENEFITS

Final program quarter page ad

Discounted technical program registrations

\$1,500

Max 2 available

TABLETOP EXHIBITOR

INCLUDES

One six-foot table with two chairs and access to electricity

One exhibit personnel badge

PDF attendee list

RECOGNITION

Exhibitor listing on the SiP webpage and final program

BENEFITS

Discounted technical program registrations

\$950-\$1,150

Max 22 available

HOW TO COMMIT TO A TABLETOP | Early Registration Discounts End May 2nd

Exhibitor Details

Only 22 exhibitor spaces are available! These WILL sell out, so book early!

Exhibitor Fees	Member	Non-Member
Early Registration <i>Booked on or before May 2nd</i>	\$950	\$1,050
Regular Registration <i>Booked after May 2nd</i>	\$1,050	\$1,150

How to Register as an Exhibitor

1. Click [here](#) to register for a tabletop space. Early registration discounts for exhibitors ends May 2nd.
2. Log into an existing account. New to IMAPS? Create a visitor profile to complete registration.
3. Select the tabletop exhibition option on the registration page.
4. Complete payment.
5. IMAPS staff will contact you one to two weeks prior to the show to confirm shipping details, request badge details, and more.

HOW TO COMMIT TO A SPONSORSHIP



Premier Sponsor

\$10,000



Presenting Sponsor

\$7,500



Start-Up Competition Sponsor

Co-Sponsor: \$2,500

Sole Sponsor: \$10,000



Sip at Wine Event Sponsor

Co-Sponsor: \$2,500

Sole Sponsor: \$5,000



Coffee Break Sponsor

\$1,500

1. Contact Brian Schieman, Executive Director, at bschieman@imaps.org with your sponsorship selection.
2. You will be provided with an invoice and instructions for payment.
3. Return payment along with a company logo file (for web and print use) and a URL for online linkage.
4. Ads are due to Brian Schieman by June 1st.
5. IMAPS staff will contact you one to two weeks prior to the show to confirm shipping details, request badge details, and more.

Don't see what you want? All sponsorships can be customized to match your Advanced SiP 2022 exposure goals.



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Contact Us

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919-293-5000

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